



Description

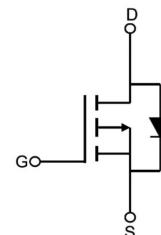
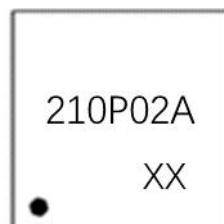
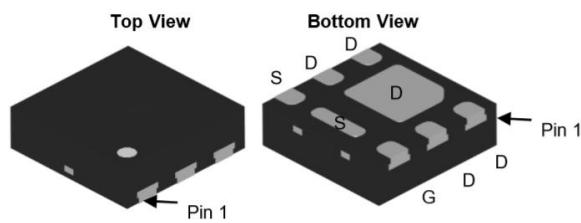
JMT P-channel Enhancement Mode Power MOSFET

Features

- -20V, -12A
- $R_{DS(ON)} < 22\text{m}\Omega$ @ $V_{GS} = -4.5\text{V}$
- $R_{DS(ON)} < 30\text{m}\Omega$ @ $V_{GS} = -2.5\text{V}$
- Advanced Trench Technology
- Provide Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

Application

- Load Switch
- PWM Application
- Power management



DFN2020-6L

Marking and pin Assignment

Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
210P02A	JMTV210P02A	TAPING	DFN2020-6L	7inch	3000	120000

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		-20	V
V_{GSS}	Gate-Source Voltage		± 12	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	-12	A
		$T_C = 100^\circ\text{C}$	-8	A
I_{DM}	Pulsed Drain Current ^{note1}		-48	A
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	4.5	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		27.8	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D = -250\mu\text{A}$	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -20\text{V}$, $V_{GS}=0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}= \pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D = -250\mu\text{A}$	-0.4	-0.7	-1.0	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS} = -4.5\text{V}$, $I_D = -10\text{A}$	-	17	22	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}$, $I_D = -5\text{A}$	-	22	30	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -10\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	2000	-	pF
C_{oss}	Output Capacitance		-	242	-	pF
C_{rss}	Reverse Transfer Capacitance		-	231	-	pF
Q_g	Total Gate Charge	$V_{DS} = -10\text{V}$, $I_D = -6\text{A}$, $V_{GS} = -4.5\text{V}$	-	15.3	-	nC
Q_{gs}	Gate-Source Charge		-	2.2	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	4.4	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -10\text{V}$, $I_D = -12\text{A}$, $V_{GS} = -4.5\text{V}$, $R_{\text{GEN}} = 2.5\Omega$	-	10	-	ns
t_r	Turn-on Rise Time		-	31	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	28	-	ns
t_f	Turn-off Fall Time		-	8	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	-12	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-48	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s = -12\text{A}$	-	-0.8	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

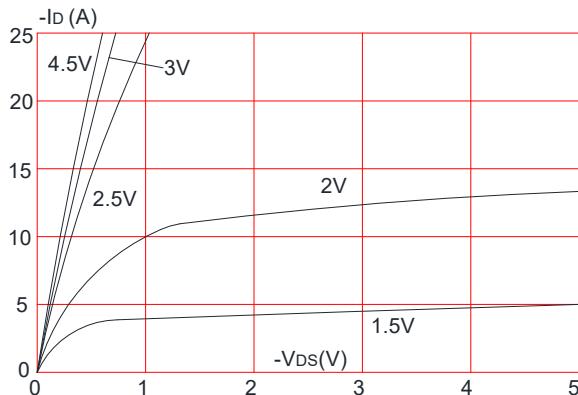


Figure 3: On-resistance vs. Drain Current

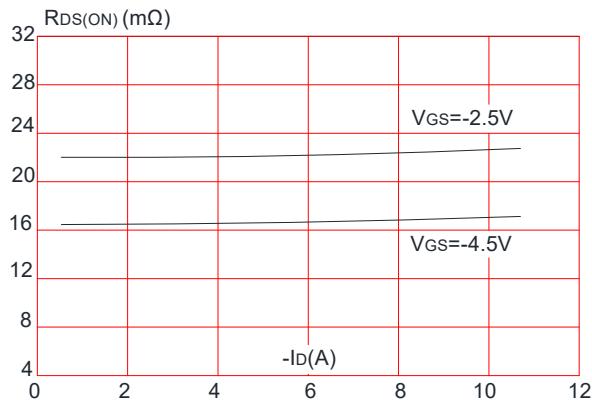


Figure 5: Gate Charge Characteristics

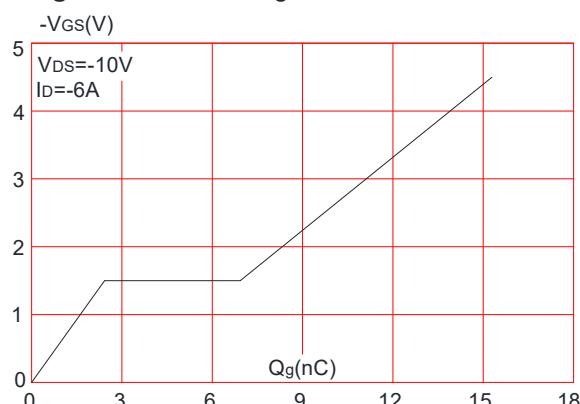


Figure 2: Typical Transfer Characteristics

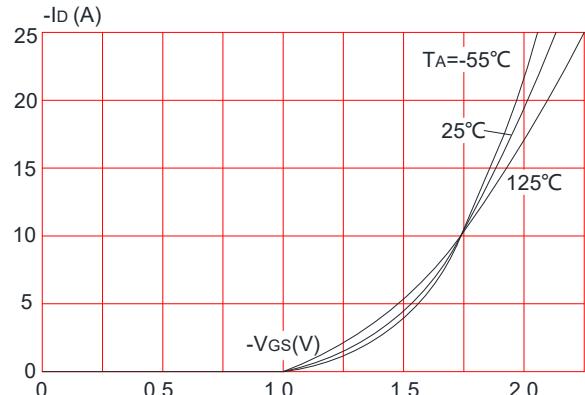


Figure 4: Body Diode Characteristics

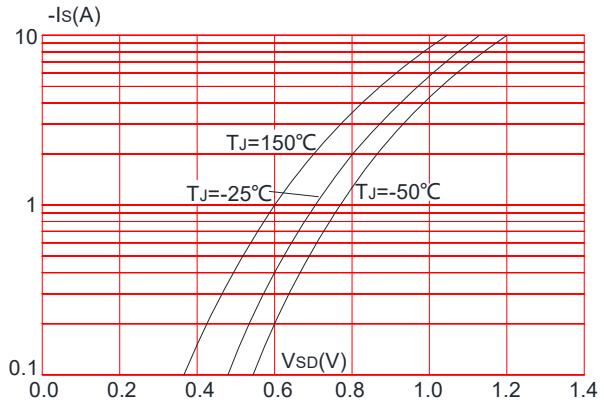


Figure 6: Capacitance Characteristics

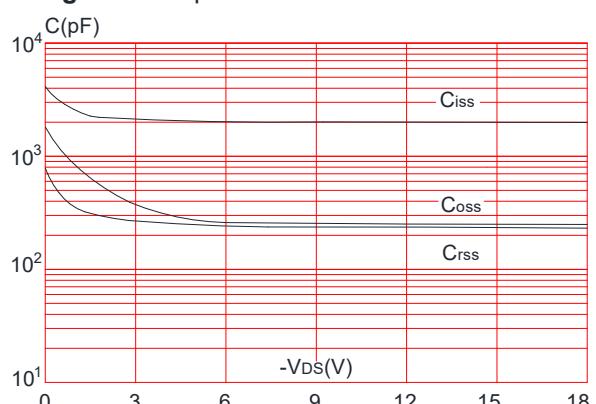


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

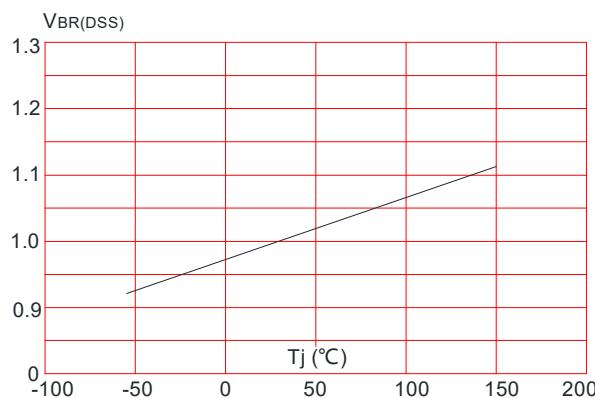


Figure 9: Maximum Safe Operating Area

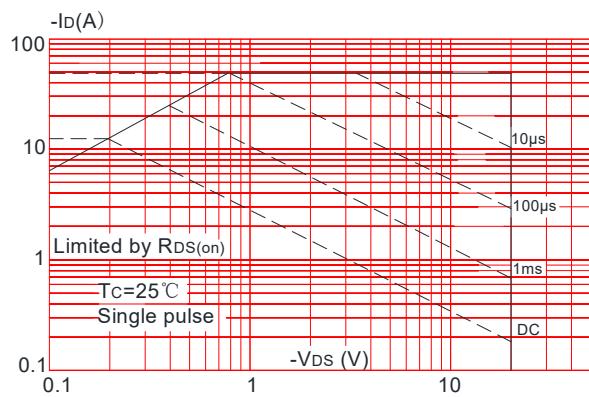


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

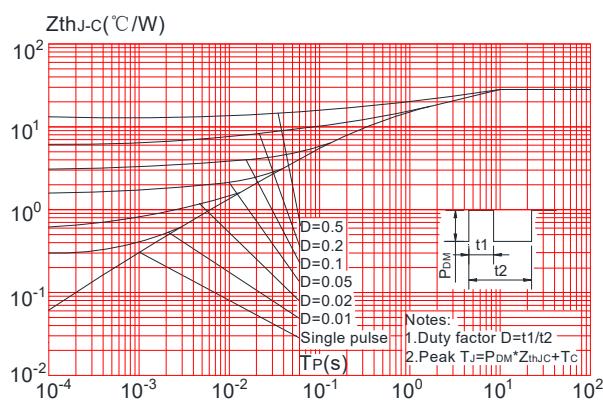


Figure 8: Normalized on Resistance vs. Junction Temperature

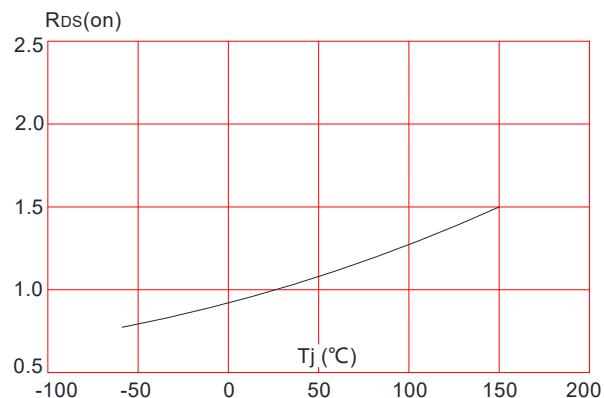
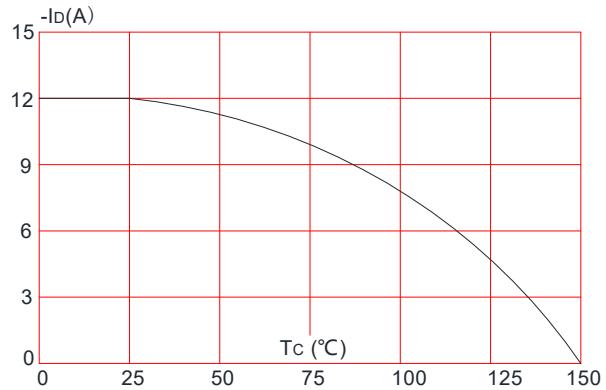
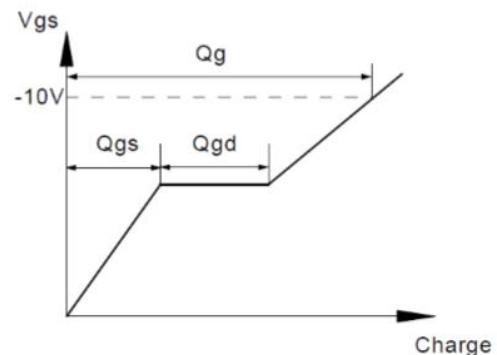
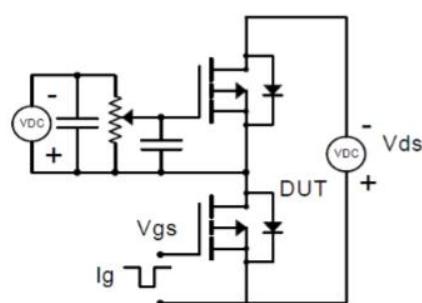


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

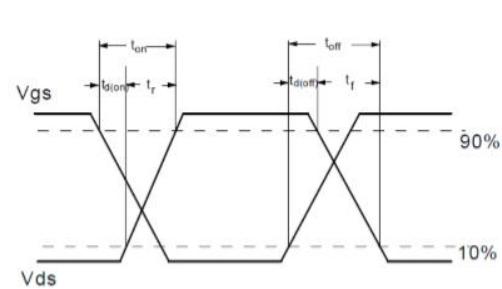
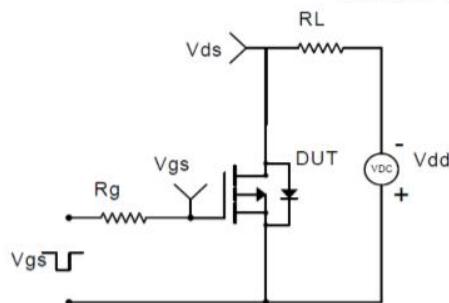


Test Circuit

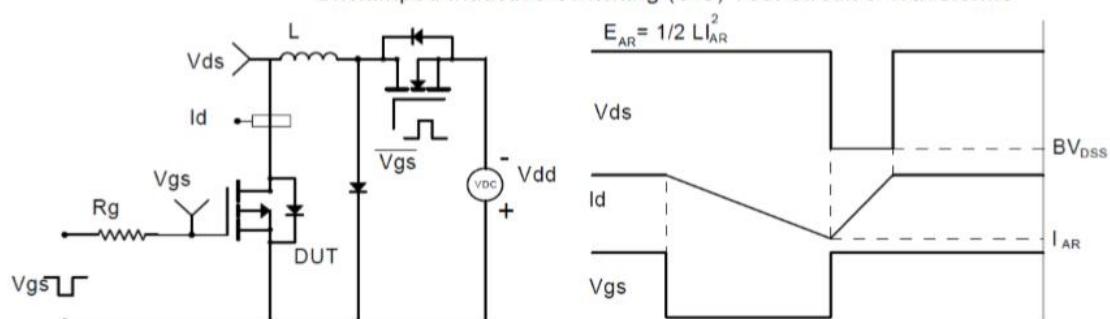
Gate Charge Test Circuit & Waveform



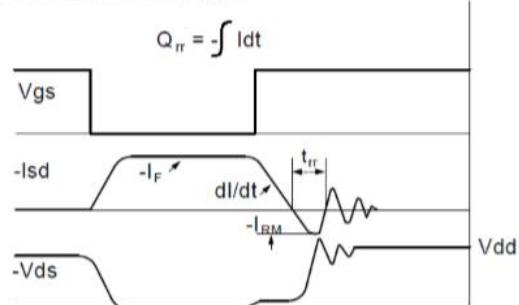
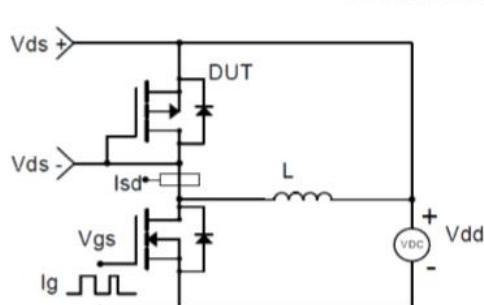
Resistive Switching Test Circuit & Waveforms



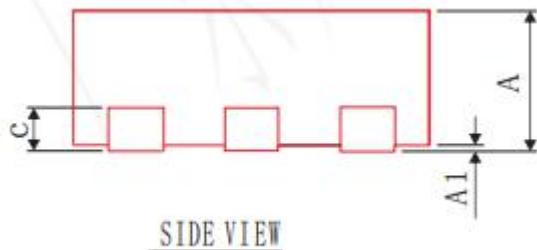
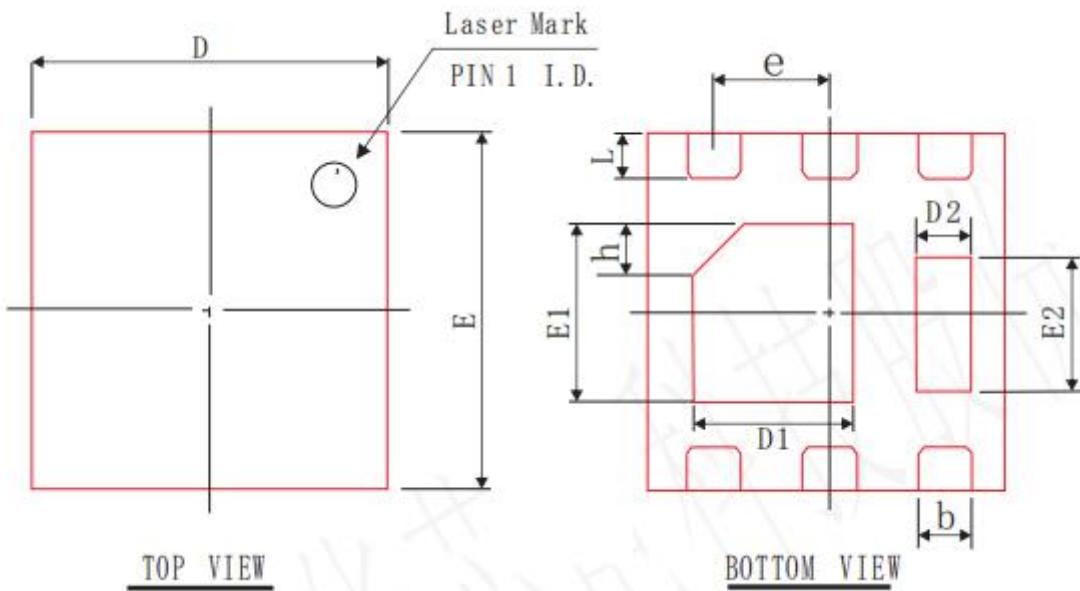
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Mechanical Data- DFN2020-6L

COMMON DIMENSIONS
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	0.55	0.60	0.65
A1	0.00	0.02	0.05
b	0.20	0.25	0.30
D	1.95	2.00	2.07
E	1.95	2.00	2.07
D1	0.80	0.90	1.00
E1	0.90	1.00	1.10
D2	0.20	0.30	0.40
E2	0.65	0.75	0.85
L	0.20	0.25	0.35
h	0.20	0.25	0.30
C	0.203 REF		
e	0.65 BSC		



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